Form PTO-1449

ASCLOSURE CITATION **INFORMA**

conformance and not considered. Include copy of this form with next communication to the applicant.

EXAMINER'S SIGNATURE

Attorney Docket No. 62020-1400

Serial No. 10/699,230

Applicant Bakir, et al.

Filing Date

(Use several sheets if necessary)					Filing Date 10/31/03		Grou TBI	•		
- "			U.S. PA	TENT DOCUMEN	TS				_	
Examiner Initials	Item	Document Number	Date	Nan	ne	Class	Subclass	Filing Date If Appropriate		
M	A	4,380,365	4/19/83	Gross		350	96.18	5/23/7	5/23/79	
	В	5,046,800	9/10/91	Blyler, Jr., et al.		385	131	10/9/9	10/9/90	
	С	5,130,356	7/14/92	Feuerherd, et al.		. 524	96	2/1/90		
	D	5,302,656	4/12/94	Kohara, et al.		524	579	4/10/9)1	
	Е	5,359,208	10/25/94	Katsuki, et al.		257	82	2/26/93		
	F	5,454,196	7/18/95	Ohkawa, et al.		522	100	7/1/9	7/1/94	
$\neg \uparrow \neg$	G	5,462,995	10/31/95	Hosaka, et al.		525	332.1	6/9/92		
	Н	5,581,414	12/3/96	Snyder		359	819	2/22/9) 3	
-	I	5,896,479	4/20/99	Vladic		385	59	4/9/9	7	
\mathcal{I}	J	6,022,498	2/8/00	Buazza, et al.		264	1.38	4/19/9) 6	
M	К	6,039,897	3/21/00	Lochhead, et al.		264	1.24	8/28/97		
	•		FOREIGN	PATENT DOCUM	ENTS					
		Document Number	Count	try	Class	Subclass	Translat	ion		
				_				Yes	N	
						<u> </u>		.]		
		OTHER DOCUM	ENTS (Includ	ling Author, Title, L	Date, Pertinent	Pages, etc	c.)			
1	L	Chen, et al.; Fully Embedded Board-Level Guided-Wave Optoelectronic Interconnects; June, 2000; Proceedings of IEEE, Vol. 88, No. 6; pp 780-793							f	
M	M Wiesmann, et al.; Singlemode Polymer Waveguides for Optical Backplanes; December 5, 1996; Ele Vol. 32, No. 25; pp 2329-2330							onics Letter	rs,	
Ka	N Barry, et al.; Highly Efficient Coupling Between Single-Mode Fiber and Polymer Optical Waveguides; A IEEE Transactions on Components, Packaging, and Manufacturing Technology - Part B, Vol. 20, No. 3;							; August, 19 3; pp 225-2	997; 28	
YR	0	Lee, et al.; Fabrication of Polymeric Large-Core Waveguides for Optical Interconnects Using a Rubber Molding Process; January, 2000; IEEE Photonics Technology Letters, Vol. 12, No. 1; pp 62-64								
	P	Schmeider, et al.; Electro-Optical Printed Circuit Board (EOPCB); 2000 Electronic Components and Technoogy Conference; pp 749-753								
	1									

DATE CONSIDERED:

JAN 2 3 2004 Form PTO-1449

EXAMINER'S SIGNATURE:

INFORMATION DISCLOSURE CITATION

Attorney Docket No. 62020-1400

Serial No. 10/699,230

Applicant Bakir, et al.

(Use several sheets if necessary)					Filing Date 10/31/03			Group TBD		
			U.S. PA	TENT DOCUMEN	TS					
Examiner Initials	ltem	Document Number	Date	Nan	ne	Class	Subclass	Filing I		
M	R	6,156,394 12/5/00 Schultz Yamasaki, et al.		et al.	427	536	4/17/	98		
	S	6,206,673	3/27/01	Lipscomb, et al.		425	174.4	5/30/	95	
/	Т	6,253,004	6/26/01	Lee, et al.		385	31	7/9/99		
(υ	6,259,567 6,262,414 6,272,275 6,281,508 6,432,328	7/10/01 . 7/17/01 . 8/7/01 . 8/28/01 . 8/13/02	Brown, et al. Mitsuhashi Cortright, et al. Lee, et al. Hamanaka, et al.		359 250 385 250 264	668	11/23/98		
	V						216			
	W						129	6/25/	6/25/99	
	х						396	2/8/9	19	
	Y						1.36	1/10/	01	
AR.	Z	6,500,603	12/31/02	Shioda		430	321	11/9/	00	
	AA									
	BB									
			FOREIGN	PATENT DOCUM	ENTS					
		Document Number	Date	Count	ıry	Class	Subclass	Transla	Translation	
								Yes	No	
			<u> </u>		· · · · · · · · · · · · · · · · · · ·				Ĺ	
· · · · · · · · · · · · · · · · · · ·		OTHER DOCUM	ENTS (Inclua	ling Author, Title, L	Date, Pertinent I	Pages, etc	c.)	······································		
	CC Schröder, et al.; Polymer Optical Interconnects for PCB; 2001; Session 13: Photonic Polymers II; pp 337-343							37-343		
M		Glukh, et al.; High performance Polymeric Materials for Waveguide Applications; August, 2000; SPIE - The International Society for Optical Engineering, inear, Nonlinear, and Power Limiting Organics, San Diego, Volume 4106; pp 1-11								
	EE	Liu, et al.; Plastic VCSEL Array Packaging and High Density Polymer Waveguides for Board and Backplane Optical Interconnect; 1998; Electronic Components and Technology Conference; pp 999-1005								
M	FF	Bakir, et al.; Sea of Dual Mode Polymer Pillar I/O Interconnections for Gigascale Integration; 2003; IEEE International Solid State Circuits Conference; 8 pages								
		Beuret, et al.; Microfabrication of 3D Multidirectional Inclined Structure by UV lithography and Electroplating; Micro Electro Mechanical Systems, 1994, MEMS'94, Proceedings, IEEE Workshop on January 25-28, 1994; pp 81-85							Micro	
M	нн	Wang, et al., Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump, Electronic Components and Technology Conference, 2001, Proceedings, 51st, 29 May-1, June 2001; pp 945-949								
		itial if citation considered, who considered. Include copy of the				raw line th	rough citatio	n if not in		

DATE CONSIDERED:

Form PTC	1440	S JAN 2 3 2004 8			Attorney Docl	ket No.	Seria	ıl No.	
	,-1442	12 JAN 23 2004 8			62020-1400			99,230	
IN	FOR	MATION DISCLO	SURE CI	TATION	Applicant				
	- 0 - 0	4910			Bakir, et al.				
		(Use several sheets i	f necessary)		Filing Date	Group TBD			
					10/31/03				
			U.S. PA	TENT DOCUMEN	TS		,	,	
Examiner	Item	Document	Date N		ie	Class	Subclass	Filing Date	
Initials	/	Number				<u> </u>		If Appropriate	
	II				·		ļ		
	11					<u> </u>			
/	KK			<u></u>		<u> </u>			
		<u></u>	FOREIGN	PATENT DOCUM	ENTS		 	· · · · · ·	
		Document	Date	Count	iry	Class	Subclass	Translation	
		Number		·.	•	:			
								· Yes	No
					•				
									<u> </u>
<u> </u>									
		OTHER DOCUM	ENTS (Includ	ling Author, Title, L	Oate, Pertinent F	ages, etc	c.)		
	LL	Bakir, et al.; Sea of Polymer Pillars: Dual-Mode Electrical Optical Input/Output Interconnections; in Proc. of Int. Interconnect Technology Conference; pp. 77-79; 2003							
M	ММ	Bakir, et al.; Sea of Polymer Pillars: Compliant Wafer-Level Electrical-Optical Chip I/O Interconnections; IEEE Photonics Technology Letters, Vol. 15, No. 11, November 2003; pp 1567-1569							
	NN	•	onnections: IFFE Photonics						
NN Bakir, et al.; Optical Transmission of Polymer Pillars for Chip I/O Optical Interconnections; IEEE Ph Technology Letters, Vol. 16, No. 1, January 2004; pp 117-119									
SR	OO Chandrasekhar, et al.; Modeling and Characterization of the Polymer Stud Grid Array (PSGA) Package: Elect Thermal and Thermo-Mechanical Qualification; IEEE Transactions on Electronics Packaging Manufacturing,								
		No. 1, January 2003; pp 54	-67			-			
		-						•	
* EXAMIN	VER: In	itial if citation considered, who	ether or not citation	on is in conformance wi	th MPEP § 609. D	raw line th	rough citation	if not in	
conformance	and no	t considered. Include copy of the	his form with nex	t communication to the	applicant.				
EXAMINE	er's si	GNATURE:	lo	DATE	CONSIDERED:	<i>i</i> フ	///	1/8.	5
L				Patent and Trad	lemark Office; U.	S. DEPA	RTMENT O	F COMMI	ERCE